

ABSTRACT

SOLDER POWDER, FLUX, SOLDER PASTE, SOLDERING METHOD,
SOLDERED CIRCUIT BOARD, AND SOLDERED JOINT PRODUCT

A flux, a solder paste, and a solder powder which can be used, each having excellent storage stability and reflow property, and further, a soldering method, a soldered circuit board, and a joint product for a circuit board and electronic parts, respondent to the tendency toward fine pitch processing and diversified parts and the like are provided. A solder powder comprises solder particles having a distribution such that the number of particles having a particle diameter of 20 μm or less is 30% or less, wherein the oxygen content is 500 ppm or less. A flux for solder paste comprises an organic acid component consisting of an organic acid ester and an ester decomposer catalyst, an organic halogen compound, a reducing agent, and a pH adjusting agent. A solder paste mainly comprises a flux and a solder powder, wherein the water content of the solder paste is 0.5% by weight or less.